

SPECIFICATION AMENDMENTS

Amend the title appearing on page 1 starting in line 1 as follows:

METHOD FOR MANUFACTURING AN ELECTRONIC COMPONENT ~~AND A~~
~~METHOD OF MANUFACTURING THE SAME~~

Amend the abstract of the disclosure appearing on page 19 starting in line 3 as follows:

A method of manufacturing an ~~An~~ electronic component ~~is obtained by forming a~~
~~primer plating layer of a material which is poorly wettable to a weld brazing material 3 on a~~
~~base member 11X of with~~ a contact 11 having a terminal section 111 for brazing and a
contact section 112, includes steps that construct a contact base member of a material that is
poorly wettable, forms a primer plating layer of a material that is poorly wettable to the weld
brazing material on the base member, and then forming forms a finish plating layer of a
material ~~which that~~ is highly wettable to the weld brazing material on the primer plating
layer, and ~~—An exposed region of the poorly wettable primer plating layer is formed~~
~~thereafter by selectively removing removes~~ a portion of the finish plating layer ~~at the~~
~~terminal section 111 and served to obtain an exposed region of the primer plating layer that~~
serves as an arresting region for arresting the weld brazing material 3 from creeping up and
migrating along the highly wettable finish plating layer in brazing the terminal section 111
to the brazing pad 22 of a wiring board 2.